WEICON F2 Epoxy Resin



Temperature resistance	-35 to +120 °C
Resistivity	7,36 · 10^12 Ωm
Thermal diffusivity (23°C)	0,737 mm²/s
Thermal conductivity	0,98 W/m·K
Specific heat capacity	0,824 J/(g·K)
ISSA-Code	75.509.11/12
IMPA-Code	812933/34

Information about surface pre-treatment and processing can be found in the manual.

Storage

Store WEICON Plastic Metal at room temperature (but up to max. +25°C) in a dry place. Unopened containers can be stored for 18 months at temperatures from +18 to +28°C (Epoxy Resin Putty max. 3 years). Opened containers should be used within 6 months.

Safety and health

When using WEICON products, the physical, safety technical, toxicological and ecological data and regulations in our EC safety data sheets (www.weicon.com) must be observed.

Available sizes:

WEICON F2 Epoxy Resin 0,2 kg
WEICON F2 Epoxy Resin 0.5 kg
WEICON F2 Epoxy Resin 2.0 kg

Accessories:

10850005	
10953001	
10953003	
10953010	
10953020	

Glass Fibre Cloth Tape, 50 mm x 1 m Processing Spatula, short Processing Spatula, long Stirrer Stainless Steel, Contour Spatula Flexy,

templates, for the repair of porous and damaged castings, for the production of prototypes and holding devices, and for pouring out

aluminium-filled

viscous

swages to test precision. WEICON F2 can be used in tool construction, model and mould making, and in many other industrial applications.

WEICON F2 is suited for the casting of models, moulds and

Technical Data

Composition	Epoxy resin aluminium-filled
Specific Properties	viscous
Colour after curing	aluminium
Mixing ratio by weight resin/hardener	100:14
Density of the mixture (200g preparation)	1,45 g/cm ³
Viscosity of the mixture	200.000 mPa·s
Consumption at a coating thickness of 1,0 mm	1,45 kg/m²
Maximium layer thickness for each working step	10 mm
Pot life at +20°C (+68°F) 200g preparation	60 min.
Curing time mechanical loads	16 h
Final hardness after	24 h
Mean strength at +25°C (+77°F) acc. to DIN EN 1465/A	STM D 1002:
Pressure	43 Mpa
Pull	14 Mpa
Bending	26 Mpa
E-Modul	1.500 - 2.000 Mpa
Shore D (ATSM D 1706)	79
Shrinkage	0,025 %
Tg after curing at room temperature	51,5 Tg (°C)
Tg after tempering (at 120 °C)	53,1 Tg (°C)
Thermoforming resistance	+55 °C

Note

The specifications and recommendations given in this technical data sheet must not be seen as guaranteed product characteristics. They are based on our laboratory tests and on practical experience. Since individual application conditions are beyond our knowledge, control and responsibility, this information is provided without any obligation. We do guarantee the continuously high quality of our products. However, own adequate laboratory and practical tests to find out if the product in question meets the requested properties are recommended. A claim cannot be derived from them. The user bears the only responsibility for non-appropriate or other than specified applications.

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